NOTES 4&5

HIH

TOP VIEW

SIDE VIEW

BOTTOM VIEW

△ 0.10 C D

E1

NOTES 4&5

0.10 C D

8X b NOTES 3&7 **⊕** 0.25**∭** C A-B D

0.10 C

С

SEATING PLANE





NOTE 6 D

E

NOTE 6 B

0.20 C D

NOTE 8

SOIC-8 EP CASE 751AC ISSUE E

DATE 05 OCT 2022

NOTES:

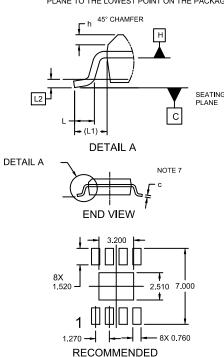
- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M. 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION 6 DOES NOT INCLUDE DAMBAR PROTRUSION, ALLOWABLE PROTRUSION SHALL BE 0.004 IN EXCESS OF MAXIMUM MATERIAL CONDITION.
- 4. DIMENSION 5 HALL BE 0.104 IN EACESS OF MAXIMUM INTERIAL CONDITION.

 4. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 PER SIDE. DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.010 mm PER SIDE.

 5. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM.

 DIMENSIONS D AND E1 ARE DETERMINED AT THE OUTERMOST EXTREMES
- OF THE PLASTIC BODY AT DATUM H.
- 6. DATUMS A AND B ARE TO BE DETERMINED AT DATUM H.
- 8. A1 IS DEFINED AS THE LOWEST POINT ON THE PACKAGE BODY.

 8. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.



	MILLIMETERS		
DIM	MIN.	NOM	MAX.
Α	1.35	1.55	1.75
A1		0.05	0.10
A2	1.35	1.50	1.65
b	0.31	0.41	0.51
С	0.17	0.21	0.23
D	4.90 BSC		
Е	6.00 BSC		
E1	3.90 BSC		
е	1.27 BSC		
F	2.24	2.72	3.20
F1		0.20 REF	
G	1.55	2.03	2.51
G1		0.46 REF	
h	0.25	0.38	0.50
L	0.40	0.84	1.27
L1	1.04 REF		
L2	0.25 REF		
Ø	0°	4°	8°

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D."

MOUNTING FOOTPRINT*

GENERIC MARKING DIAGRAM*



XXXXXX = Specific Device Code = Assembly Location Υ = Year WW = Work Week

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present and may be in either location. Some products may not follow the Generic Marking.

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